# Gap Pad® 1500

### Thermally Conductive, Unreinforced Gap Filling Material

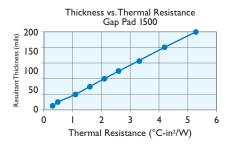
#### **Features and Benefits**

- Thermal conductivity: 1.5 W/m-K
- Unreinforced construction for additional compliancy
- Conformable, low hardness
- · Electrically isolating



Gap Pad 1500 has an ideal filler blend that gives its low-modulus characteristic that maintains optimal thermal performance yet still allows for easy handling. The natural tack on both sides of the material allows for good compliance to adjacent surfaces of components, minimizing interfacial resistance.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 1500			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Black	Black	Visual
Reinforcement Carrier	_	_	_
Thickness (inch) / (mm)	0.020 to 0.200	0.508 to 5.080	ASTM D374
Inherent Surface Tack (I- or 2-sided)	2	2	_
Density (g/cc)	2.1	2.1	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	40	40	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	45	310	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	_
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1000 Hz)	5.5	5.5	ASTM D150
Volume Resistivity (Ohm-meter)	10"	1011	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470
1) Thirty second delay value Shore 00 hardness scale			

<sup>1)</sup> Thirty second delay value Shore 00 hardness scale.

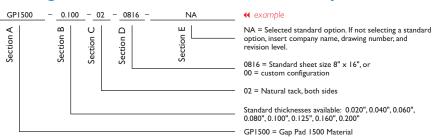
#### **Typical Applications Include:**

- Telecommunications
- Computer and peripherals
- Power conversion
- RDRAM™ memory modules / chip scale packages
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader

## **Configurations Available:**

• Sheet form and die-cut parts

#### **Building a Part Number**



Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others.

**Standard Options** 

<sup>2)</sup> Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116.